RA6T2 Group

MCB-RA6T2 User's Manual

Renesas RA Family RA6 Series

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The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power is supplied until the power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

6. Voltage application waveform at input pin

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.)

7. Prohibition of access to reserved addresses

Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.

8. Differences between products

Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.



Renesas RA Family

MCB-RA6T2 User's Manual

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1. Overview

MCB-RA6T2 is a CPU board for motor control evaluation. By using this product in combination with an inverter board, motor control using RA6T2 can be easily performed.

1.1 Presupposition and precautions of this document

- 1. Experience of using tools: This document assumes that the user has used terminal emulation program of Integrated Development Environment (IDE) such as e2 studio before.
- 2. Knowledge about the development subject: This document assumes that the user has a basic knowledge to modify the sample project regarding MCU and embedded system.
- 3. Before using this product, wear an antistatic wrist strap. If you touch this product with static charge on your body, a device failure may occur, or operation may become unstable
- 4. All screen shots provided in this document is for reference. Actual screen displays may differ depending on the software and development tool version which you use.



2. Product Contents

This kit consists of the following parts.

- 1. CPU Board (RTK0EMA270C00000BJ) x1
- 2. USB Cable x1
- 3. Screw x4
- 4. Standoff x4



Figure 2-1 Product contents

3. Product Order Information

Product No. to order MCB-RA6T2 : RTK0EMA270C00000BJ



4. Hardware Configuration and Default Setting

4.1 Hardware configuration

The specifications of the CPU board are shown below.

Table 4-1 CPU Board Specification

item		Specification				
Product name		CPU Board				
Board part No.		RTK0EMA270C00000BJ				
Compatible inve	erter board	RTK0EM0000B12020BJ				
External view						
		Note: The actual product may differ from this photo.				
Mounted MCU	Product group	RA6T2 group				
	Product No.	R7FA6T2BD3CFP				
	CPU maximum	240MHz				
	operating frequency					
	Bit count	32 bit				
	Package / Pin number	LFQFP / 100 pin				
	RAM	64K byte				
MCU input clock	<	10MHz (Generate with external crystal oscillator)				
Input power sup	ply voltage	DC 5V Select one from the below • Power is supplied from compatible inverter board • Power is supplied from USB connector				
Debugger		J-Link-OB (Onboard debugger circuit)				
Connector		 Inverter board connector (2 sets) USB connector for J-Link OB SCI connector for Renesas Motor Workbench communication Through hole for CAN communication Through hole for SPI communication 20 pin through hole for Arm debugger 				
Switch		MCU reset switch				
LED		User-controllable LED x6, Power LED x1				
Board size		109mm (W) x 109mm (L)				
Operating temp	erature	Room temperature				
Operating humi		No condensation allowed				
EMC Directive		Europe : EN61326-1 : 2013 Class A				





4.2 Block diagram



Figure 4-1 Block Diagram of CPU Board



4.3 Board Layout



Figure 4-2 CPU Board Layout

4.4 Standoffs and Screws

Before using this product, assemble the included standoffs and screws as shown below.



Figure 4-3 Standoffs and Screws assembly



4.5 Jumper pin setting

Default settings and functions of the jumper pins (JP1~JP25) are as follows.

Jumper pin	Default setting	Function
JP1	2-3pin short	1-2pin short : INV1 IPS CSNIRQN 2-3pin short : INV1 Encoder Z
JP2	2-3pin short	1-2pin short : INV2 PFC current detection (for HV INV) 2-3pin short : INV2 IPS A
JP3	2-3pin short	1-2pin short : INV2 AC input voltage detection (for HV INV) 2-3pin short : INV2 IPS A#/Encoder A#
JP4	1-2pin short	1-2pin short : INV1 HALL U 2-3pin short : INV1 IPS A
JP5	1-2pin short	1-2pin short : INV1 HALL V 2-3pin short : INV1 IPS A#/Encoder A#
JP6	1-2pin short	1-2pin short : INV2 V-phase voltage detection 2-3pin short : INV2 IPS B
JP7	2-3pin short	1-2pin short : INV1 PFC current detection (for HV INV) 2-3pin short : INV1 IPS B#
JP8	2-3pin short	1-2pin short : INV2 IPS CSNIRQN 2-3pin short : INV2 Encoder Z
JP9	1-2pin short	1-2pin short : INV2 W-phase voltage detection 2-3pin short : INV2 IPS B#/Encoder B#
JP10	2-3pin short	1-2pin short : INV1 AC input voltage detection (for HV INV) 2-3pin short : INV1 IPS B#/Encoder B#
JP11	1-2pin open 3-4pin open 5-6pin open	
JP12	1-2pin open	1-2pin short : Disable J-Link OB 1-2pin open : Enable J-Link OB
JP13	1-2pin short 3-4pin short 5-6pin short 7-8pin short	
JP14	1-2pin short	1-2pin short : Enable RA6T2 2-3pin short : Disable RA6T2
JP15, JP16	1-2pin open	1-2pin short : Enable pull-up for I2C 1-2pin open : Disable pull-up for I2C
JP17	2-3pin short	1-2pin short : INV1 IPS A 2-3pin short : INV1 Encoder A
JP18	2-3pin short	1-2pin short : INV1 IPS B 2-3pin short : INV1 Encoder B
JP19	1-2pin short	1-2pin short : INV1 W-phase voltage detection 2-3pin short : INV1 W-phase current detection (PGAVSS)
JP20	1-2pin short	1-2pin short : INV1 V-phase voltage detection 2-3pin short : INV1 V-phase current detection (PGAVSS)
JP21	2-3pin short	1-2pin short : INV2 IPS A 2-3pin short : INV2 Encoder A
JP22	2-3pin short	1-2pin short : INV2 IPS B 2-3pin short : INV2 Encoder B
JP23, JP24, JP25	1-2pin open	1-2pin open : Enable LPF for current sensing 1-2pin short : Disable LPF for current sensing

Table 4-2 Jumper pin setting





Figure 4-4 Default jumper pin setting

4.6 Connection Example

Figure 4-5 shows a connection example when using this product in combination with a Renesas inverter board kit (MCI-LV-1, P/N: RTK0EM0000S04020BJ) and a communication board (MC-COM, P/N: RTK0EMXC90S00000BJ).



Figure 4-5 Connection Example



5. CPU Board Specification

This section describes the specification of the CPU Board.

5.1 Functions

5.1.1 Power supply

When not connected to the inverter board, power should be supplied from the USB connector. When connecting to the inverter board, power supply from the USB connector or from the inverter board will be automatically selected. USB power supply has priority.

5.1.2 Onboard debugger

This product has the onboard debugger circuit, J-Link On-Board (hereinafter called "J-Link-OB"). You can write a program (firmware) of RA6T2 with it. When you write a program, connect the CPU board to PC with USB cable. J-Link-OB operates as debugger equivalent to J-Link. If connecting from Integrated Development Environment or flash programming tool (e.g. J-Flash Lite by SEGGER), set the type of debugger (tool) to "J-Link".

5.1.3 Inverter board connector

Two inverter boards can be connected to this board: the 1st inverter board is connected with CN4 and CN5, and the 2nd inverter board is connected with CN6 and CN7. The pin assignments of the connectors are shown in Table 5-1, Table 5-2, Table 5-3 and Table 5-4. Note that these tables show default connection setting for the ports with jumper switches.

Pin No Pin Function		RA6T2 Pin	Pin No	Pin Function	RA6T2 Pin
1	SPARE1	-	2	AGND	- (AVSS)
3	VPN	PA06/AN006	4	AGND	- (AVSS)
5	IU	PA04/AN004	6	PGAVSSU	PA05/PGAVSS2
7	IV	PA02/AN002	8	PGAVSSV	PA03/AN003
9	IW	PA00/AN000	10	PGAVSSW	PA01/AN001
11	VU	PA07/AN007	12	VV	PA03/AN003
13	VW	PA01/AN001	14	AGND	- (AVSS)
15	VAC	PB10/AN028	16	IPFC	PE15/AN027
17	VR	PB00/AN008	18	AGND	- (AVSS)
19	AVCC	- (AVCC)	20	AVCC	- (AVCC)
21	AGND	- (AVSS)	22	AGND	- (AVSS)
23	VCC	- (VCC)	24	VCC	- (VCC)
25	GND	- (VSS)	26	GND	- (VSS)
27	UN	PB05/GTIOC4B_B	28	GND	- (VSS)
29	UP	PB04/GTIOC4A_B	30	GND	- (VSS)
31	VN	PB07/GTIOC5B_B	32	GND	- (VSS)
33	VP	PB06/GTIOC5A_B	34	GND	- (VSS)

Table 5-1 1st Inverter board connector (CN4) pin assignment



Pin No Pin Function RA		RA6T2 Pin	Pin No	Pin Function	RA6T2 Pin
1	WN	PB09/GTIOC6B_B	2	GND	- (VSS)
3	WP	PB08/GTIOC6A_B	4	GND	- (VSS)
5	SPARE2	-	6	SPARE3	-
7	SPARE4	-	8	SPARE5	-
9	BUS_POWER_IN	-	10	INV_CONNECTED	-
11	SAFE_LOCK	-	12	OC#	PC13/GTETRGD
13	PFCERROR	P001/IRQ2	14	PFCPWM	PB14/GTIOC1A
15	VRL	PE01	16	SW1	PD04
17	SW2	PD07	18	LED1	PD01
19	LED2	PD02	20	LED3	PD03
21	HALL_U	PC04/IRQ10_B	22	HALL_V	PC05/IRQ11_B
23	HALL_W	PB01/IRQ1_B	24	MISO0/SIO_SDA	PC11/MISOB_B
25	SCK0/SCK_SCL	PC10	26	CSN_IRQN/ENC_Z	PE00/GTETRGA
27	IPS_A	PC04	28	IPS_A#/ENC_A#	PC05/IRQ11_B
	ENC_A PC14/GTIOC3A_D				
29	IPS_B	PE15	30	IPS_B#//ENC_B#	PB10/AN028
	ENC_B PC15/GTIOC3B_D				
31	GND	- (VSS)	32	GND	- (VSS)
33	+5V	-	34	+5V	-

Table 5-2 1st Inverter board connector (CN5) pin assignment

Table 5-3 2nd Inverter board connector (CN7) pin assignment

Pin No	lo Pin Function RA6T2 Pin		Pin No	Pin Function	RA6T2 Pin
1	SPARE1	-	2	AGND	- (AVSS)
3	VPN	PE13/AN025	4	AGND	- (AVSS)
5	IU	PB02/AN018	6	PGAVSSU	P002/PGAVSS3
7	IV	PE08/AN020	8	PGAVSSV	-
9	IW	PE09/AN021	10	PGAVSSW	-
11	VU	PE10/AN022	12	VV	PE11/AN023
13	VW	PE12/AN024	14	AGND	- (AVSS)
15	VAC	PC03/AN015	16	IPFC	PC02/AN014
17	VR	PE14/AN026	18	AGND	- (AVSS)
19	AVCC	- (AVCC)	20	AVCC	- (AVCC)
21	AGND	- (AVSS)	22	AGND	- (AVSS)
23	VCC	- (VCC)	24	VCC	- (VCC)
25	GND	- (VSS)	26	GND	- (VSS)
27	UN	PC09/GTIOC7B_A	28	GND	- (VSS)
29	UP	PC08/GTIOC7A_A	30	GND	- (VSS)
31	VN	PA09/GTIOC8B_A	32	GND	- (VSS)
33	VP	PA08/GTIOC8A_A	34	GND	- (VSS)



Pin No	Pin Function	RA6T2 Pin	Pin No	Pin Function	RA6T2 Pin
1	1 WN PA11/GTIOC9B_A		2	GND	- (VSS)
3	WP	PA10/GTIOC9A_A	4	GND	- (VSS)
5	SPARE2	-	6	SPARE3	-
7	SPARE4	-	8	SPARE5	-
9	BUS_POWER_IN	-	10	INV_CONNECTED	-
11	SAFE_LOCK	-	12	OC#	PA12/GTETRGB
13	PFCERROR	P000/IRQ0	14	PFCPWM	PB15/GTIOC1B_A
15	VRL	PD11	16	SW1	PC00
17	SW2	PC01	18	LED1	PD15
19	LED2	PC06	20	LED3	PC07
21	HALL_U	PD12/IRQ12_B	22	HALL_V	PD13/IRQ13_B
23	HALL_W	PD14/IRQ13_B	24	MISO0/SIO_SDA	PC11/MISOB_B
25	SCK0/SCK_SCL	PC10	26	CSN_IRQN/ENC_Z	PD10/GTETRGC
27	IPS_A	PC02	28	IPS_A#/ENC_A#	PC03/AN015
	ENC_A	PD08/GTIOC2A_A			
29	IPS_B	PE11	30	IPS_B#//ENC_B#	PE12/AN024
	ENC_B	PD09/GTIOC2B_A			
31	GND	- (VSS)	32	GND	- (VSS)
33	+5V	-	34	+5V	-

Table 5-4 2nd Inverter board connector	r (CN6) pin assignment
--	------------------------

The connection for CPU board and inverter board is shown in Figure 5-1.



(1) CPU Board + INV Board (connected with CN4, CN5)



(2) CPU Board + INV Board (connected with CN6, CN7)



(3) CPU Board + INV Board x2

Figure 5-1 Connection for CPU board and inverter board

5.1.4 Serial communication

For serial communication using Renesas Motor Workbench, the CPU board has SCI connector. Pin assignment for SCI connector is listed in Table 5-5.

Table 5-5 SCI connector (CN10) pin assignment

Pin No.	Pin Function	RA6T2 Connection Pin
1	GND	-
2	MCU RXD	PD06/RXD9_A
3	MCU TXD	PD05/TXD9_A
4	VCC	-

5.1.5 Reset circuit

This product has a reset circuit to enable power-on reset or external reset on MCU. Push the tact switch (SW1) to externally reset MCU.



5.1.6 LED

This product has six ports and LEDs, so that they can be used for program debug and the system. LED switches on when output from the corresponding port is "LOW" and switches off when output is "HIGH". Pin assignment for corresponding LEDs is listed in Table 5-6.

RA6T2 port		LED1	LED2	LED3	LED4	LED5	LED6
PD01	Output HIGH	OFF	-	-	-	-	-
	Output LOW	ON	-	-	-	-	-
PD02	Output HIGH	-	OFF	-	-	-	-
	Output LOW	-	ON	-	-	-	-
PD03	Output HIGH	-	-	OFF	-	-	-
	Output LOW	-	-	ON	-	-	-
PD15	Output HIGH	-	-	-	OFF	-	-
	Output LOW	-	-	-	ON	-	-
PC06	Output HIGH	-	-	-	-	OFF	-
	Output LOW	-	-	-	-	ON	-
PC07	Output HIGH	-	-	-	-	-	OFF
	Output LOW	-	-	-	-	-	ON

Table 5-6 LED pin assignment

5.1.7 CAN Communication

This product has through holes for CAN communication. Note that CAN driver is not equipped. Pin assignment for CAN communication connector is listed in Table 5-7.

Table 5-7 CAN communication pin assignment (CN8)

Pin No	RA6T2 pin
1	VCC
2	PB13/CTX0_E
3	PB12/CRX0_E
4	VSS

5.1.8 SPI communication

This product has through holes for SPI communication. Pin Assignment for SPI communication connector is listed in Table 5-8.

Table 5-8 SPI communication pin assignment (CN9)

Pin No	RA6T2 pin
1	PD00_SS0
2	PC12_MOSI0
3	PC11_MISO0/SIO_SDA
4	PC10_SCK0/SCK_SCL
5	VSS
6	VCC



5.2 RA6T2 pin function list

Table 5-9 RA6T2 pin function list

Pin number	RA6T2 pin function	Signal function
1	PE02/TRCLK/CMPOUT0_C/GTOVLO_C/GTIOC7B_B/GTIOC8A_E/GT	ARM debugger
	CPPO8/SCK0_B/DE0_D/SCK3_A/DE3_A/RSPCKB_C/CLKOUT_C	
2	PE03/TRDATA0/CMPOUT1_C/GTOWLO_C/GTIOC8A_B/GTIOC9A_E/	ARM debugger
	GTCPPO6/RXD0_B/CTS3_A/SSLB0_C/GTODFMA	
3	PE04/TRDATA1/CMPOUT2_C/GTOUUP_C/GTIOC8B_B/GTIOC7B_E/	ARM debugger
	GTCPPO9/TXD0_B/SS_CTS_RTS3_A/DE3_A/SSLB1_C/GTODFMB	
4	PE05/TRDATA2/CMPOUT3_C/GTOVUP_C/GTIOC9A_B/GTIOC8B_E/	ARM debugger
	GTCPPO2/SS_CTS_RTS0_B/DE0_B/RXD3_A/MISOB_C/GTODFMC	
5	PE06/TRDATA3/GTOWUP_C/GTIOC9B_B/GTCPPO3/CTS0_B/TXD3_	ARM debugger
	A/MOSIB_C/GTODFMD	
6	VCC	Power
7	PC13/GTETRGD/NMI	INV1 over current
8	PC14/ADTRG0_C/CMPOUT012_B/AGTWIO0_C/GTETRGA/GTIOC3A	INV1 Encoder_A
Ũ	_D/GTCPPO0/GTADSM0/GTCPPO4/IRQ14_A/GTODFMC	
9	PC15/ADTRG1_C/CMPOUT345_B/AGTWIO1_C/GTETRGB/GTIOC3B	INV1 Encoder_B
0	_D/GTCPPO1/GTADSM1/GTCPPO7/IRQ15_A/GTODFMD	
10	VSS	Power
10	VCC	Power
12	P212/EXTAL	
		Xtal
13	P213/XTAL/IRQ0_C	Xtal
14	RES	ARM debugger
15	PC00/AN012 (AN012)/PGAOUT0/IVCMP00/IRQ11DS	INV2 SW1
16	PC01/AN013 (AN013)/PGAOUT1/IVCMP10/IRQ12DS	INV2 SW2
17	PC02/AN014 (AN014)/PGAOUT2/IVCMP20/IRQ13DS	INV2 PFC current
		detection/IPS_A
18	PC03/AN015 (AN015)/PGAOUT3/IVCMP30/IRQ14DS	INV2 PFC current
		detection/IPS_A #
19	P000/AN016 (AN016)/IVREF0/IRQ0_D	INV2 PFC over current
		detection
20	VREFL0	Power
21	VREFH0	Power
22	P001/AN017 (AN017)/IVREF1/IRQ2_C	INV1 PFC over curren
		detection
23	PA00/AN000 (AN000)/PGAIN0/IVCMP02 / IVCMP03/IRQ0DS	INV1 W-phase current
		detection
24	PA01/AN001 (AN001)/PGAVSS0/IRQ1_A	INV1 W-phase voltage
		detection/PGAVSS_
		W
25	PA02/AN002 (AN002)/PGAIN1/IVCMP12 / IVCMP13/IRQ2_A	INV1 V-phase current
20		detection
26	PA03/AN003 (AN003)/PGAVSS1/IRQ3_A	INV1 V-phase voltage
20		detection/PGAVSS_
		V
27	AVSS0	Power
	AVSS0	
28		Power
29	PA04/AN004 (AN004)/PGAIN2/IVCMP22 / IVCMP23/IRQ4_A	INV1 U-phase curren
		detection
30	PA05/AN005 (AN005)/PGAVSS2/IRQ5_A	INV1 PGAVSS_U
31	PA06/AN006 (AN106)/DA0/IRQ6_A	INV1 bus voltage
		detection
32	PA07/AN007 (AN107)/DA1/IRQ7_A	INV1 W-phase voltage
		detection
33	PC04/AN010 (AN110)/DA2/IRQ10_B	INV1 HALL_U/IPS_A
34	PC05/AN011 (AN111)/DA3/IRQ11_B	INV1 HALL_V/IPS_A#
35	PB00/AN008 (AN108)/PGAOUT0 / PGAOUT2/IRQ0_A	INV1 VR1 voltage
		detection
36	PB01/AN009 (AN109)/PGAOUT1 / PGAOUT3/IRQ1_B	INV1 HALL_W



Pin number	RA6T2 pin function	Signal function
37	PB02/AN018 (AN118)/PGAIN3/IVCMP32 / IVCMP33/IRQ15DS	INV2 U-phase current detection
38	P002/AN019 (AN119)/PGAVSS3	INV2 PGAVSS_U
39	PE08/AN020/AN120/ADTRG0_E/CMPOUT012_C/GTIV_B/GTIOC3A_	INV2 V-phase current
	B/GTETRGC/GTADSM0/SSLA3_C/KR00_E/GTODFMON	detection
40	PE09/AN021/AN121/ADTRG1_E/CMPOUT345_C/GTIW_B/GTIOC3B_	INV2 W-phase current
	B/GTETRGD/GTADSM1/CACREF_F/SSLA2_C/KR01_E	detection
41	PE10/AN022/AN122/GTOULO_B/GTIOC2A_B/GTIOC4A_C/GTIOC7A	INV2 U-phase voltage
	_D/SSLA1_C/KR02_E	detection
42	PE11/AN023/AN123/GTOUUP_B/GTIOC2B_B/GTIOC5A_C/GTIOC8A	INV2 V-phase voltage
	_D/SSLA0_C/KR03_E	detection /IPS_B
43	PE12/AN024/AN124/GTOVLO_B/GTIOC1A_B/GTIOC6A_C/GTIOC9A_	INV2 V-phase voltage
	D/RSPCKA_C/KR04_E	detection/IPS_B#
44	PE13/AN025/AN125/GTOVUP_B/GTIOC1B_B/GTIOC4B_C/GTIOC7B	INV2 bus voltage
	_D/MISOA_C/KR05_E	detection
45	PE14/AN026/AN126/GTOWLO_B/GTIOC0A_B/GTIOC5B_C/GTIOC8B	INV2 VR1 voltage
	_D/MOSIA_C/KR06_E	detection
46	PE15/AN027/AN127/GTOWUP_B/GTIOC0B_B/GTIOC6B_C/GTIOC9B	INV1 PFC current
	_D/RXD4_A/KR07_E	detection/IPS_B
47	PB10/AN028/AN128/GTIU_C/GTETRGA/GTETRGB/GTCPPO4/GTCP	INV1 PFC voltage
	PO7/CACREF_C/TXD4_A/CTS3_B/IRQ10DS/VCOUT	detection/IPS_B#
48	VCL1	Power
49	VSS	Power
50	VCC	Power
51	PB12/ADTRG0_B/GTETRGA/GTIOC0A_A/GTIOC4A_F/CRX0_E/SCK 4_A/DE4_A/RXD3_B/SSLB0_A/IRQ2_B	CAN_RX
52	PB13/GTOULO_A/GTIOC0B_A/GTIOC7A_C/GTIOC5A_F/CTX0_E/CT	CAN_TX
	S4_A/TXD3_B/RSPCKB_A/IRQ3_B	
53	PB14/GTOVLO_A/GTIOC1A_A/GTIOC8A_C/GTIOC6A_F/SS_CTS_RT S4_A/DE4_A/SCK3_B/DE3_B/SDA0_C/MISOB_A/IRQ4_B	INV2 PFCPWM1
54	PB15/GTOWLO_A/GTIOC1B_A/GTIOC9A_C/GTIOC4B_F/RXD4_A/SS	INV1 PFCPWM2
	_CTS_RTS3_B/DE3_B/SCL0_C/MOSIB_A/IRQ5_B	
55	PD08/GTIOC2A_A/CTS2_B/TXD1_A/SSLB1_A/KR00_D	INV2 Encoder_A
56	PD09/GTIOC2B_A/SS_CTS_RTS2_B/DE2_B/RXD1_A/SSLB2_A/KR0	INV2 Encoder_B
	1_D	
57	PD10/GTETRGC/GTIOC3A_A/SCK2_C/DE2_C/SCK1_A/DE1_A/SSLB	INV2 Encoder_Z
	3_A/KR02_D	
58	PD11/GTIOC3B_A/RXD2_C/CTS1_A/KR03_D	INV2 Relay control
59	PD12/GTIOC4A_A/TXD2_C/SS_CTS_RTS1_A/DE1_A/SCL1_D/KR04_ D/IRQ12_B/GTODFMA	INV2 HALL_U
60	PD13/GTIOC4B_A/SCK4_C/DE4_C/SCK9_C/DE9_C/SDA1_D/KR05_	INV2 HALL_V
	D/IRQ13_B/GTODFMB	
61	PD14/GTIOC5A_A/RXD4_C/RXD9_C/SCL0_F/KR06_D/IRQ14_B/GTO DFMC	INV2 HALL_W
62	PD15/GTIOC5B_A/TXD4_C/TXD9_C/DE9_C/SDA0_F/KR07_D/IRQ15	INV2 LED1
	_B/GTODFMD	
63	PC06/AGTWO0_B/GTETRGD/GTIOC6A_A/GTIOC5B_F/TXD2_B/SS_	INV2 LED2
	CTS_RTS9_C/DE9_C/SCL1_E/IRQ6_B	
64	PC07/AGTWEE0_B/GTETRGA/GTIOC6B_A/RXD2_B/CTS9_C/SDA1_	INV2 LED3
	E/IRQ7_B	
65	PC08/AGTWOA0_B/GTIV_C/GTIOC7A_A/CACREF_D/SCK2_B/DE2_	INV2 PWM U-phase
	B/SS_CTS_RTS3_C/DE3_C/SCL0_D (SCL0_E)/SSLA3_B/IRQ8_B	(Upper)
66	PC09/AGTWOB0_B/GTIW_C/GTIOC7B_A/GTIOC8A_F/SS_CTS_RTS	INV2 PWM U-phase
	2_B/DE2_B/CTS3_C/SDA0_D	(Lower)
	(SDA0_E)/SSLA2_B/IRQ9_B/CLKOUT_B	
67	PA08/CMPOUT2_A/AGTWIO0_B/GTOUUP_A/GTIOC8A_A/GTIOC7B_	INV2 PWM V-phase
	C/GTIOC2A_C/GTIOC9A_F/SCK0_A/DE0_A/SCK1_C/DE1_C/SCL0_D	(Upper)
	/SSLA1_B/KR00_B/IRQ8_A/CLKOUT_A	
68	PA09/CMPOUT3_A/GTOVUP_A/GTIOC8B_A/GTIOC8B_C/GTIOC2B_	INV2 PWM V-phase
	C/GTIOC7B_F/TXD0_A/SCL1_C/SSLA0_B/KR01_B/IRQ9_A	(Lower)
69	PA10/CMPOUT0_A/GTOWUP_A/GTIOC9A_A/GTIOC9B_C/GTIOC3A	INV2 PWM W-phase



Pin number	RA6T2 pin function	Signal function
	C/GTIOC8B_F/RXD0_A/SDA1_C/RSPCKA_B/KR02_B/IRQ10_A	(Upper)
70	PA11/CMPOUT1_A/GTETRGD/GTIOC9B_A/GTETRGC/GTIOC3B_C/	INV2 PWM W-phase
10	CTX0_A/CTS0_A/RXD1_C/MOSIA_B/KR03_B/IRQ11_A	(Lower)
71	PA12/ADTRG1_A/GTETRGB/GTCPP00/GTCPP02/GTADSM0/GTCP	INV2 over current
	PO7/CACREF_A/CRX0_A/SS_CTS_RTS0_A/DE0_A/TXD1_C/MISOA	detection/PFC over
	B/KR04_B/IRQ12_A/GTODFMA	current detection
72	PA13/TMS/SWDIO/TMS/SWDIO/AGTWO0_A/SCK0_C/DE0_C/SS_CT	ARM debugger
12	S_RTS1_C/DE1_C	
73	VCL2	Power
74	VSS	Power
75	VCC	Power
76	PA14/TCK/SWCLK/AGTWO1_A/TXD0_C/SCK9_B/DE9_B	ARM debugger
77	PA15/TDI/ADTRG0_A/CMPOUT012_A/GTETRGB/GTADSM1/GTCPP	ARM debugger
	O4/RXD0_C/RXD9_B/SSLA0_A/KR02_A/IRQ1_C/GTODFMB	ARIVI debuggei
78	PC10/CMPOUT0_B/AGTWIO1_B/TXD1_B/SCL0_B[w/5VToI]/RSPCKB	SS
10	B/KR05_B/IRQ6DS	33
79	PC11/CMPOUT1_B/AGTWOA1_B/RXD1_B/SDA0_B[w/5VTol]/MISOB	MOSI
79		MOSI
80	_B/KR06_B/IRQ7DS PC12/CMPOUT2_B/AGTWOB1_B/GTCPP06/GTCPP09/TXD4_B/SC	
00	K1_B/DE1_B/MOSIB_B/KR07_B/IRQ8DS/GTODFMON	MISO/SIO_SDA
81	PD00/GTADSM0/GTCPPO4/CRX0 F/CTS2 A/RXD3 C/SSLB0 B/KR	SCK0/SCK_SCL
01	00_C	SCRU/SCR_SCL
82	PD01/GTADSM1/GTCPPO7/CTX0_F/SS_CTS_RTS2_A/DE2_A/TXD3	INV1 LED1
02		
0.2	C/SSLB1_B/KR01_C PD02/CMPOUT3_B/AGTWEE1_B/GTCPPO0/GTCPPO2/RXD4_B/SC	
83		INV1 LED2
0.4	K3_C/DE3_C/KR02_C/IRQ9DS/CLKOUT_D PD03/CMPOUT0_D/GTCPPO5/GTCPPO0/SCK4_B/DE4_B/CTS9_A/S	INV1 LED3
84		INVI LED3
05	SLB2_B/KR03_C/ PD04/CMPOUT1_D/GTCPPO8/GTCPPO1/SS_CTS_RTS4_B/DE4_B/	INV1 SW1
85		
86	SS_CTS_RTS9_A/DE9_A/SSLB3_B/KR04_C PD05/GTADSM0/GTCPPO3/TXD9_A/SDA1_B[w/5VToI]/SSLA3_A/KR0	DMM/ communication
80	5_C	RMW communication
87	D06/GTCPPO4/RXD9_A/SCL1_B[w/ 5VTol]/SSLA2_A/KR06_C	RMW communication
88	PD07/GTADSM1/GTCPP07/SCK9_A/DE9_A/SSLA1_A/KR07_C	INV1 SW2
89	PB03/TD0/TRACESWO/ADTRG1 B/CMPOUT345 A/AGTWO1 B/GTI	ARM debugger
09	OC4A_D/GTCPPO1/GTCPPO3/CRX0_D/TXD2_A/TXD9_B/RSPCKA_	ARIVI debuggei
	A/KR03_A/IRQ0_B/GTODFMON	
90	PB04/AGTWOA0 A/GTIOC4A B/GTIOC5A D/GTIOC0A C/CACREF	INV1 PWM U-phase
90	B/CTX0_D/RXD2_A/RXD3_D/MISOA_A/KR04_A/IRQ13_A/VCOUT	(Upper)
91	PB05/AGTWOB0_A/GTIU_A/GTIOC4B_B/GTIOC6A_D/GTIOC0B_C/C	INV1 PWM U-phase
91	RX0_B/SCK2_A/DE2_A/TXD3_D/MOSIA_A/KR05_A/IRQ3DS/GTODF	(Lower)
	MON	
92	PB06/AGTWOA1_A/GTIV_A/GTIOC5A_B/GTIOC4B_D/GTIOC1A_C/C	INV1 PWM V-phase
52	TX0_B/TXD0_D/SS_CTS_RTS3_D/DE3_D/SCL0_A[HSw/5VTol]/KR06	(Upper)
	_A/IRQ4DS/GTODFMA	
93	PB07/AGTWOB1_A/GTIW_A/GTIOC5B_B/GTETRGC/GTIOC1B_C/RX	INV1 PWM V-phase
50	D0_D/SS_CTS_RTS1_D/DE1_D/SDA0_A[HSw/5VTol]/KR07_A/IRQ5D	(Lower)
	S/GTODFMB	
		ARM debugger
94		
94 95	P201/MD PB08/AGTWIO0_A/GTIOC6A_B/GTIOC5B_D/GTIOC2A_D/CRX0_C/B	
94 95	PB08/AGTWIO0_A/GTIOC6A_B/GTIOC5B_D/GTIOC2A_D/CRX0_C/R	INV1 PWM W-phase
95	PB08/AGTWIO0_A/GTIOC6A_B/GTIOC5B_D/GTIOC2A_D/CRX0_C/R XD4_C/RXD1_D/SCL1_A[w/5VTol]/KR00_A/IRQ1DS/GTODFMC	INV1 PWM W-phase (Upper)
-	PB08/AGTWIO0_A/GTIOC6A_B/GTIOC5B_D/GTIOC2A_D/CRX0_C/R XD4_C/RXD1_D/SCL1_A[w/5VTol]/KR00_A/IRQ1DS/GTODFMC PB09/AGTWIO1_A/GTIOC6B_B/GTIOC2B_D/CTX0_C/TXD4_C/TXD1	INV1 PWM W-phase (Upper) INV1 PWM W-phase
95 96	PB08/AGTWIO0_A/GTIOC6A_B/GTIOC5B_D/GTIOC2A_D/CRX0_C/R XD4_C/RXD1_D/SCL1_A[w/5VTol]/KR00_A/IRQ1DS/GTODFMC PB09/AGTWIO1_A/GTIOC6B_B/GTIOC2B_D/CTX0_C/TXD4_C/TXD1 _D/SDA1_A [w/5VTol]/KR01_A/IRQ2DS/GTODFMD	INV1 PWM W-phase (Upper) INV1 PWM W-phase (Lower)
95	PB08/AGTWIO0_A/GTIOC6A_B/GTIOC5B_D/GTIOC2A_D/CRX0_C/R XD4_C/RXD1_D/SCL1_A[w/5VTol]/KR00_A/IRQ1DS/GTODFMC PB09/AGTWIO1_A/GTIOC6B_B/GTIOC2B_D/CTX0_C/TXD4_C/TXD1 _D/SDA1_A [w/5VTol]/KR01_A/IRQ2DS/GTODFMD PE00/ADTRG0_D/AGTWEE0_A/GTETRGA/GTIOC4A_F/GTADSM0/G	INV1 PWM W-phase (Upper) INV1 PWM W-phase
95 96 97	PB08/AGTWIO0_A/GTIOC6A_B/GTIOC5B_D/GTIOC2A_D/CRX0_C/R XD4_C/RXD1_D/SCL1_A[w/5VTol]/KR00_A/IRQ1DS/GTODFMC PB09/AGTWIO1_A/GTIOC6B_B/GTIOC2B_D/CTX0_C/TXD4_C/TXD1 _D/SDA1_A [w/5VTol]/KR01_A/IRQ2DS/GTODFMD PE00/ADTRG0_D/AGTWEE0_A/GTETRGA/GTIOC4A_F/GTADSM0/G TCPPO5/CACREF_E/TXD0_E/TXD9_D/SSLB3_	INV1 PWM W-phase (Upper) INV1 PWM W-phase (Lower) INV1 Encoder_Z
95 96	PB08/AGTWIO0_A/GTIOC6A_B/GTIOC5B_D/GTIOC2A_D/CRX0_C/R XD4_C/RXD1_D/SCL1_A[w/5VTol]/KR00_A/IRQ1DS/GTODFMC PB09/AGTWIO1_A/GTIOC6B_B/GTIOC2B_D/CTX0_C/TXD4_C/TXD1 _D/SDA1_A [w/5VTol]/KR01_A/IRQ2DS/GTODFMD PE00/ADTRG0_D/AGTWEE0_A/GTETRGA/GTIOC4A_F/GTADSM0/G TCPPO5/CACREF_E/TXD0_E/TXD9_D/SSLB3_ PE01/ADTRG1_D/AGTWEE1_A/GTOUL0_C/GTIOC7A_B/GTIOC4B_	INV1 PWM W-phase (Upper) INV1 PWM W-phase (Lower)
95 96 97	PB08/AGTWIO0_A/GTIOC6A_B/GTIOC5B_D/GTIOC2A_D/CRX0_C/R XD4_C/RXD1_D/SCL1_A[w/5VTol]/KR00_A/IRQ1DS/GTODFMC PB09/AGTWIO1_A/GTIOC6B_B/GTIOC2B_D/CTX0_C/TXD4_C/TXD1 _D/SDA1_A [w/5VTol]/KR01_A/IRQ2DS/GTODFMD PE00/ADTRG0_D/AGTWEE0_A/GTETRGA/GTIOC4A_F/GTADSM0/G TCPPO5/CACREF_E/TXD0_E/TXD9_D/SSLB3_	INV1 PWM W-phase (Upper) INV1 PWM W-phase (Lower) INV1 Encoder_Z



6. Design and Manufacture Information

You can obtain information on the design and manufacture of this product from renesas.com.

7. Website and Support

In order to learn, download tools and documents, apply technical support for RA family MCU and its kit, visit the below Web site.

- · RA Product Information renesas.com/ra
- · RA Product Support Forum renesas.com/ra/forum
- · Renesas Support renesas.com/support



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		Page	Summary
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